

## Patent Abstracts of Japan

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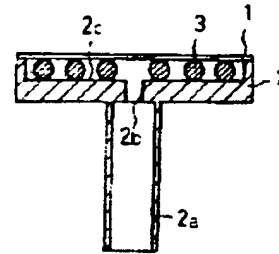
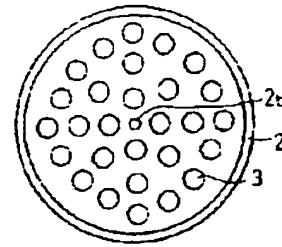
APPLICATION DATE : 15-05-90  
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APPLICANT : MITSUBISHI ELECTRIC CORP;

INVENTOR : SHIROMIZU RYOJI;

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TITLE : WAFER CHUCK



ABSTRACT : PURPOSE: To prevent contamination of a semiconductor wafer from the surface of a chuck and improper suction due to adherence of a foreign matter and to improve productivity by securing many supporting members having spherical surfaces for supporting at one point a wafer on the upper surface of the chuck.

CONSTITUTION: A wafer 1 and one side of a T-shaped chuck 2 are formed in disc state, and the entire surface is formed in a recess state in a predetermined depth except several mm of the outer periphery. A through hole 2a is formed at the other side. A suction port 2b formed at the center of the recess 2c of the chuck 2 and the upper surfaces of many spherical supporting members 3 secured to the entire surface of the recess 2c are aligned in the same plane. The wafer 1 is supported by the many members 3 at one point supports in a state that the wafer 1 is sucked to the surface of the chuck 2. Thus, contamination of the wafer from the surface of the chuck 2 and improper suction of a foreign matter due to the adherence to the surface of the chuck 2, and damage can be prevented.

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